Multilayer Ceramic Chip Capacitors

1 of 3 Creation Date : April 18, 2017 (GMT)

C1005X7R1H103K050BB









TDK item description C1005X7R1H103KT****

Applications	Commercial Grade Please refer to Part No. CGA2B3X7R1H103K050BB for Automotive use.	
Feature	General (Up to 50V)	
Series	C1005 [EIA 0402]	
Status	Production (Not Recommended for New Design)	



	Size
Length(L)	1.00mm ±0.05mm
Width(W)	0.50mm ±0.05mm
Thickness(T)	0.50mm ±0.05mm
Terminal Width(B)	0.10mm Min.
Terminal Spacing(G)	0.30mm Min.
Recommended Land Pattern (PA)	0.30mm to 0.50mm
Recommended Land Pattern (PB)	0.35mm to 0.45mm
Recommended Land Pattern (PC)	0.40mm to 0.60mm

Electrical Characteristics		
Capacitance	10nF ±10%	
Rated Voltage	50VDC	
Temperature Characteristic	X7R(±15%)	
Dissipation Factor (Max.)	5%	
Insulation Resistance (Min.)	10000ΜΩ	

Other		
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Punched (Paper)Taping [180mm Reel]	
Package Quantity	10000pcs	

[!] Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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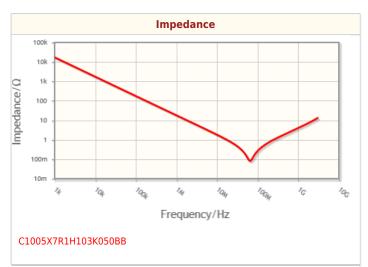


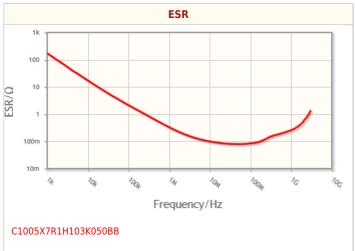


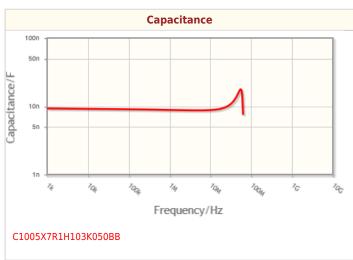


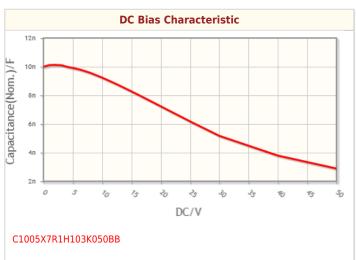


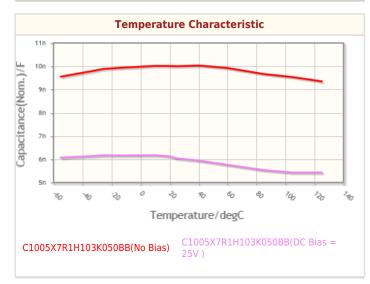
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

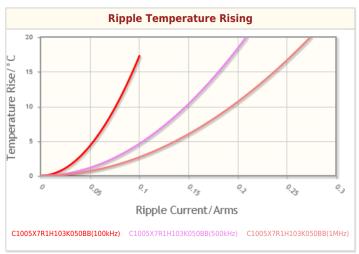












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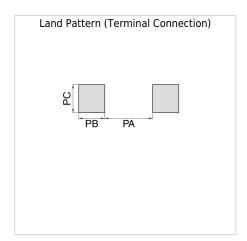






Associated Images

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